

WEE, wafer edge expose  
 LHP, lo temp hot plate  
 CPL, chill plate  
 CHP, chilling hot plate  
 ADH, HMDS dispense and hot plate  
 UNC, unicassette station  
 PRA, the main robot  
 IRA, interface robot  
 CRA, Cassette stage robot  
 CWH, cup wash  
 DEV, developer  
 COT, coater  
 TCT, top coater  
 SBU, stationary buffer  
 EIS, wafer handoff to the stepper  
 TCP, transition chill plate  
 TRS, transition station  
 PUP, engineering cassette station

3-4 WEE		2-24 LHP	2-29 HHP	2-14 HHP	1-4 UNC	
3-5 EIS	3-0 IRA	2-23 CHP	2-28 LHP	2-13 LHP		
		2-22 CHP	2-27 LHP	2-12 LHP		
		2-21 CHP	2-26 LHP	2-11 CPL		
		2-20	2-0 PRA	2-10 CWH		
		2-19 CPL		2-9 CPL		
		2-18		2-8 TRS-R		
		2-17 CPL		2-7 TCP-R		
		2-16 TRS	2-6			
		2-15 CPL	2-5 ADH			
		3-3 SBU		2-3 DEV		2-4 DEV
3-2 SBU		2-1 COT		2-2 TCT	1-3 UNC	
3-1 THS				1-5 PUP		1-2 UNC
					1-1 UNC	

(OW × OD × OH)